

Welcome to the introduction of Hirose's new DF57 series of ultra low profile, wire to board connector systems. This presentation will provide an in-depth explanation of the DF57 series features and benefits



Hirose's DF57 Series is an ultra-low profile wire-to-board connector system suitable for applications requiring up to 2.5 amperes per line. Key features include: 1.2 millimeter contact pitch, and a height of just 1.4 millimeter when mated. The DF57 series is also designed for space saving on the PCB. The unique "Swing-lock" mating feature assures a more secure connection. The operating current is up to 2.5 amperes when using #28 gauge wire. The contacts of the PCB mount header are designed to prevent solder wicking in to the contact mating area. Contact retention strength is designed to prevent accidental pull-out of the wire and contact when under load. All materials conform to RoHS.



With a contact pitch of 1.2 millimeter, low profile design and efficient PCB real estate layout, the DF57 is suitable for tight packaging requirements. The DF57 is available in contact counts from 2 to 6 positions. Compatible stranded wire sizes are #28 to #34 AWG. Please refer to the Hirose datasheet for specific details of compatible wire types.



The design of the "Swing Lock" mechanism in the DF57 assures that a secure connection is maintained when properly mated. Care should be taken to follow the mating and un-mating sequence to assure best performance and durability of the connectors as described here.



The unique locking structure actually strengthens as a tension load is place in the direction of the wires. Accidental un-mating if the wires are pulled upward is resisted up to 5 Newtons, but will not result in significant damage to the connector if over ridden. The mating sequence is begun by first pressing the rear, wire end, of the connector into the slots of the header body.



To complete the mating sequence of the connector, the friction lock must be engaged by rocking the connector down and forward. A clear tactile and audible feedback indicates a successful mating of the connector. The total locking mechanism assures a secure mating condition, minimizing float between the connector halves.



The design of the wire crimped contacts features two points of contact assuring good contact normal force maximizing electrical current capacity. By insert-molding the header contacts into the housing, air-gaps between the housing material and contacts are eliminated, thus preventing the potential for solder-wicking during the PCB solder reflow process.



The design for the DF57 contact produces low contact resistance, strong current capacity and durable blade type male contact. Compatible wire sizes range from #28 to #34, with maximum insulation outside diameter from 0.63 millimeters to 0.32 millimeters. The maximum current rating of 2.5 amperes per pin is applicable to the 2 position; higher pin counts must be de-rated accordingly due to total temperature rise potential.



The improved contact retention design of the DF57 creates a double secured retention tab when the connectors are mated. When mated, the housing side contact retention tab is compressed against the header bottom further securing the contact and protecting the contact cavity from particulate intrusion. This effectively prevents the contacts from being pulled loose under tension in all but the most extreme cases.



Shown here is the basic PCB land pattern and dimensions for the DF57 Series.



Due to the ultra-low profile design, the DF57 is a good consideration where tight packaging is a must. Applications include connections for battery power, speaker, buzzer or vibrator-motor connections, illumination devices and touch panel overlay connections. The small size makes the DF57 a good candidate for replacement of flexible printed circuits where higher current or other considerations may make stranded wire a more desirable choice.

		Specif	icati	ions			
Material	and Finish	-					
COMPONENT		MATERIAL		FINISH / REMARKS			
Housing	Header	LCP	l	UL94V-0, Black			
	Socket	PBT		UL94V-0, White			
Header Contact		Brass		Tin-plated over Nickel under plating			
Crimp Contact		Phosphor bronze	-	Tin-plated			
Metal Fitting		Brass		Tin-plated over Nickel under plating			
Performa	ance Charact	eristics					
Rated Current			AWG#2	28 AWG#	¢30	AWG#32	AWG#34
		2 pos.	2.5 Am	ps 15 An	1.5 Amps	1.0 Amps	0.8 Amps
		3 pos.	2.0 Am	ps 1.5 All			
		4, 5 and 6 pos.	1.5 Am	ps 1.0 An	nps	0.8 Amps	0.5 Amps
Rated Voltage		2 to 6 pos.	50 V AC	/ DC			
		2 pos. (Middle pin of 3 pos. is removed)	pos. (Middle pin of pos. is removed) 100 V AC / DC				
Operating Temperature		- 35 °C to + 85 °C*					
Contact Resistance		10 m Ω MAX. at 20 mV, 1 mA					
Insulation Resistance		100 M Ω MIN. (100 V DC)					
Withstanding Voltage		500 V AC for 1 minute					
Applicable Cable		AWG #28 to 34, ø0.32 to 0.63 mm					
Durability		30 cycles (Insertion / Withdrawal)					

The performance and materials specifications are shown here. Included are the derated operating current for each pin count and wire size.



In summary; the new DF57 Series, Wire-to-Board connector system from Hirose is an ultra-low profile design, which makes efficient use of printed circuit board real estate. The unique "Swing Lock" mechanism produces a very reliable connection that resists unwanted pull-out or un-mating. With an operating electrical current of up to 2.5 amperes per pin, the DF57 provides best-in-class current density for its size. The header design integrates solder wicking prevention. All materials are RoHS compliant.